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SNLS234I-OCTOBER 2006-REVISED JANUARY 2009

DS15BA101 1.5 Gbps Differential Buffer with Adjustable Output Voltage

Check for Samples: DS15BA101

FEATURES

- Data Rates from DC to 1.5+ Gbps
- Differential or Single-ended Input
- Adjustable Output Amplitude
- Single 3.3V Supply
- Industrial -40°C to +85°C Temperature
- Low Power: 150 mW (typ) at 1.5 Gbps
- Space-saving 3 x 3 mm WSON-8 Package

APPLICATIONS

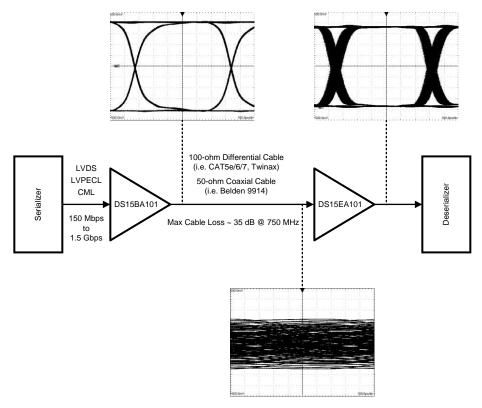
- Cable Extension Applications
- Level Translation
- Signal Buffering and Repeating
- Security Cameras

DESCRIPTION

The DS15BA101 is a high-speed differential buffer for cable driving, level translation, signal buffering, and signal repeating applications. Its fully differential signal path ensures exceptional signal integrity and noise immunity and it drives both differential and single-ended transmission lines at data rates in excess of 1.5 Gbps.

Output voltage amplitude is adjustable via a single external resistor for level translation and cable driving applications into 50-ohm single-ended and 100-ohm differential mode impedances.

The DS15BA101 is powered from a single 3.3V supply and consumes 150 mW (typ) at 1.5 Gbps. It operates over the full -40° C to $+85^{\circ}$ C industrial temperature range and is available in a space saving 3x3 mm WSON-8 package.





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Typical Application

DS15BA101

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STRUMENTS

XAS



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾

Supply Voltage	-0.5V to 3.6V	
Input Voltage (all inputs)	-0.3V to V _{CC} +0.3V	
Output Current	28 mA	
Storage Temperature Range	−65°C to +150°C	
Junction Temperature	+150°C	
Lead Temperature (Soldering 4 Sec)	+260°C	
Deckage Thermel Decisteres	θ _{JA} WSON-8	+90.7°C/W
Package Thermal Resistance	θ_{JC} WSON-8	+41.2°C/W
ESD Rating (HBM)	5 kV	
ESD Rating (MM)	250V	

(1) "Absolute Maximum Ratings" are those parameter values beyond which the life and operation of the device cannot be guaranteed. The stating herein of these maximums shall not be construed to imply that the device can or should be operated at or beyond these values. The table of "Electrical Characteristics" specifies acceptable device operating conditions.

Recommended Operating Conditions

Supply Voltage (VCC – GND):	3.3V ±5%
Operating Free Air Temperature (T _A) DS15BA101SD	−40°C to +85°C

DC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified.⁽¹⁾⁽²⁾

Symbol	Parameter	Conditions	Reference	Min	Тур	Max	Units
V _{ICM}	Input Common Mode Voltage	See ⁽³⁾	IN+, IN-	0.8		V _{CC} – V _{ID} /2	V
V _{ID}	Differential Input Voltage Swing			100		2000	mV _{P-P}
V _{OS}	Output Common Mode Voltage		OUT+, OUT-		V _{CC} – V _{OUT} /2		V
V _{OUT}	Output Voltage	Single-ended, 25Ω load $R_{VO} = 953\Omega \ 1\%$,			400		mV _{P-P}
		Single-ended, 25Ω load $R_{VO} = 487\Omega \ 1\%$,			800		mV _{P-P}
I _{CC}	Supply Current	See ⁽⁴⁾			45	49	mA

(1) Current flow into device pins is defined as positive. Current flow out of device pins is defined as negative. All voltages are stated referenced to GND.

Typical values are stated for V_{CC} = +3.3V and T_A = +25°C. Specification is guaranteed by characterization.

(3)

Maximum I_{CC} is measured at V_{CC} = +3.465V and T_A = +70°C. (4)



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AC Electrical Characteristics

Over Supply Voltage and Operating Temperature ranges, unless otherwise specified⁽¹⁾.

Symbol	Parameter	Conditions	Reference	Min	Тур	Max	Units
DR _{MAX}	Maximum Data Rate	See ⁽²⁾	IN+, IN-	1.5	2.0		Gbps
t _{LHT}	Output Low to High Transition Time	20% - 80% ⁽³⁾	OUT+, OUT-		120	220	ps
t _{HLT}	Output High to Low Transition Time	*			120	220	ps
t _{PLHD}	Propagation Low to High Delay	See ⁽²⁾		0.95	1.10	1.35	ns
t _{PHLD}	Propagation High to Low Delay	See ⁽²⁾		0.95	1.10	1.35	ns
t _{TJ}	Total Jitter	1.5 Gbps			26		ps _{P-P}

(1)

(2)

Typical values are stated for V_{CC} = +3.3V and T_A = +25°C. Specification is guaranteed by characterization. Specification is guaranteed by characterization and verified by test. (3)

CONNECTION DIAGRAM

IN+	1		8	OUT+
IN-	2	DAP	7	OUT-
GND	3	(GND)	6	GND
R_{VO}	4		5	VCC

Figure 2. 8-Pad WSON See NGQ Package

PIN DESCRIPTIONS

Pin #	Name	Description
1	IN+	Non-inverting input pin.
2	IN-	Inverting input pin.
3	GND	Circuit common (ground reference).
4	R _{VO}	Output voltage amplitude control. Connect a resistor to V_{CC} to set output voltage.
5	V _{CC}	Positive power supply (+3.3V).
6	GND	Circuit common (ground reference).
7	OUT-	Inverting output pin.
8	OUT+	Non-inverting output pin.

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DEVICE OPERATION

INPUT INTERFACING

The DS15BA101 accepts either differential or single-ended input. The inputs are self-biased, allowing for simple AC or DC coupling. DC-coupled inputs must be kept within the specified common-mode range. The IN+ and IN-pins are self-biased at approximately 2.1V with $V_{CC} = 3.3V$. The following three figures illustrate typical DC-coupled interface to common differential drivers.

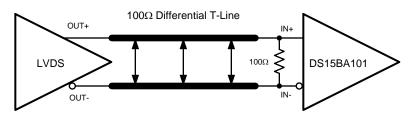


Figure 3. Typical LVDS Driver DC-Coupled Interface to DS15BA101 Input

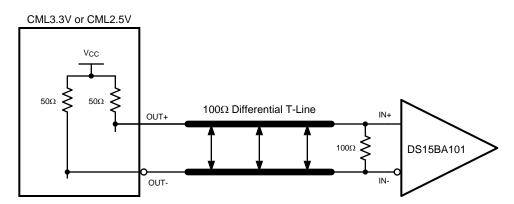


Figure 4. Typical CML Driver DC-Coupled Interface to DS15BA101 Input

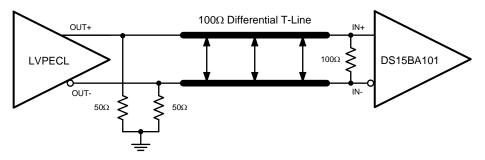


Figure 5. Typical LVPECL Driver DC-Coupled Interface to DS15BA101 Input

OUTPUT INTERFACING

The DS15BA101 uses current mode outputs. Single-ended output levels are 400 mV_{P-P} into AC-coupled 100 Ω differential cable (with R_{VO} = 953 Ω) or into AC-coupled 50 Ω coaxial cable (with R_{VO} = 487 Ω). Output level is controlled by the value of the R_{VO} resistor connected between the R_{VO} and V_{CC}.

The R_{VO} resistor should be placed as close as possible to the R_{VO} pin. In addition, the copper in the plane layers below the R_{VO} network should be removed to minimize parasitic capacitance. The following figure illustrates typical DC-coupled interface to common differential receivers and assumes that the receivers have high impedance inputs. While most receivers have a common mode input range that can accomodate CML signals, it is recommended to check respective receiver's datasheet prior to implementing the suggested interface implementation.





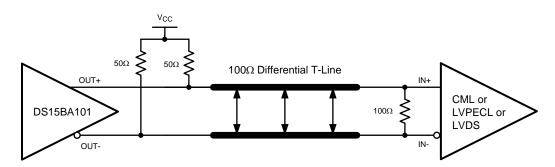


Figure 6. Typical DS15BA101 Output DC-Coupled Interface to an LVDS, CML or LVPECL Receiver

CABLE EXTENDER APPLICATION

The DS15BA101 together with the DS15EA101 form a cable extender chipset optimized for extending serial data streams from serializer/deserializer (SerDes) pairs and field programmable gate arrays (FPGAs) over 100 Ω differential (i.e. CAT5e/6/7 and twinax) and 50 Ω coaxial cables. Setting correct DS15BA101 output amplitude and proper cable termination are keys for optimal operation. The following two figures show recommended chipset configuration for 100 Ω differential and 50 Ω coaxial cables.

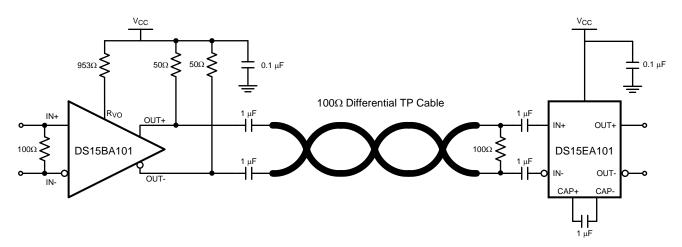
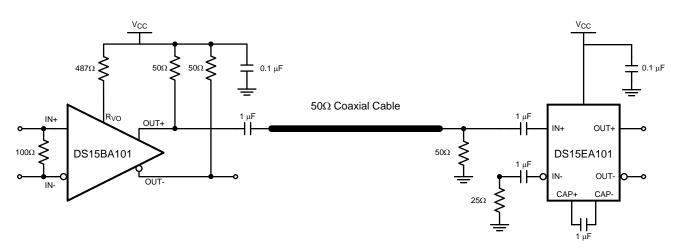


Figure 7. Cable Extender Chipset Connection Diagram for 100Ω Differential Cables



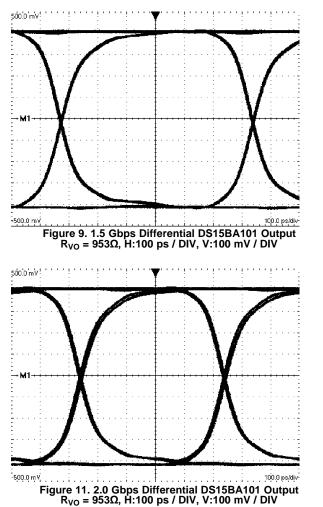


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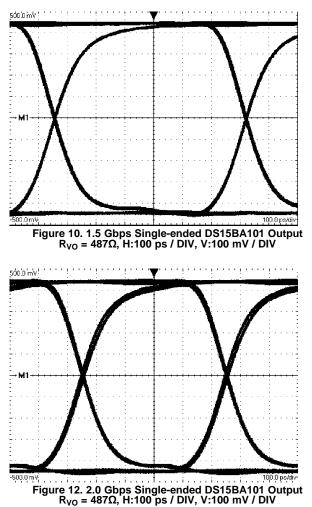


REFERENCE DESIGN

There is a complete reference design (P/N: DriveCable02EVK) available for evaluation of the cable extender chipset (DS15BA101 and DS15EA101). For more information, visit http://www.ti.com/tool/drivecable02evk.



Typical Performance



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24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing			(2)		(3)		(4)	
DS15BA101SD/NOPB	ACTIVE	WSON	NGQ	8	1000	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	BA101	Samples
DS15BA101SDE/NOPB	ACTIVE	WSON	NGQ	8	250	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	BA101	Samples
DS15BA101SDX/NOPB	ACTIVE	WSON	NGQ	8	4500	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	BA101	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS15BA101SD/NOPB	WSON	NGQ	8	1000	178.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
DS15BA101SDE/NOPB	WSON	NGQ	8	250	178.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1
DS15BA101SDX/NOPB	WSON	NGQ	8	4500	330.0	12.4	3.3	3.3	1.0	8.0	12.0	Q1

TEXAS INSTRUMENTS

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PACKAGE MATERIALS INFORMATION

26-Mar-2013

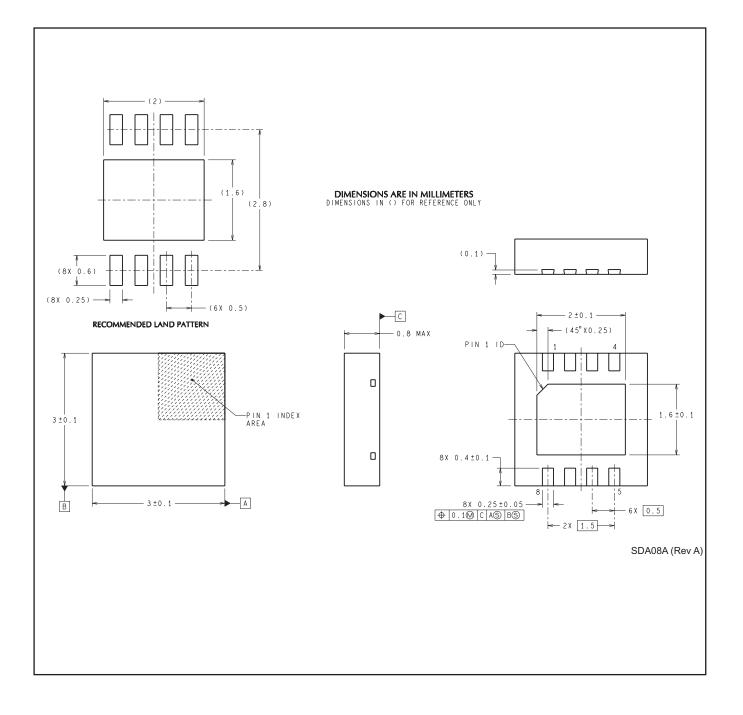


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS15BA101SD/NOPB	WSON	NGQ	8	1000	213.0	191.0	55.0
DS15BA101SDE/NOPB	WSON	NGQ	8	250	213.0	191.0	55.0
DS15BA101SDX/NOPB	WSON	NGQ	8	4500	367.0	367.0	35.0

MECHANICAL DATA

NGQ0008A





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